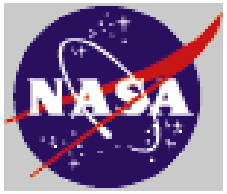
Jet Propulsion Laboratory

National Aeronautics & Space Administration

California Institute of Technology



Ball Grid Array Assembly Reliability

by

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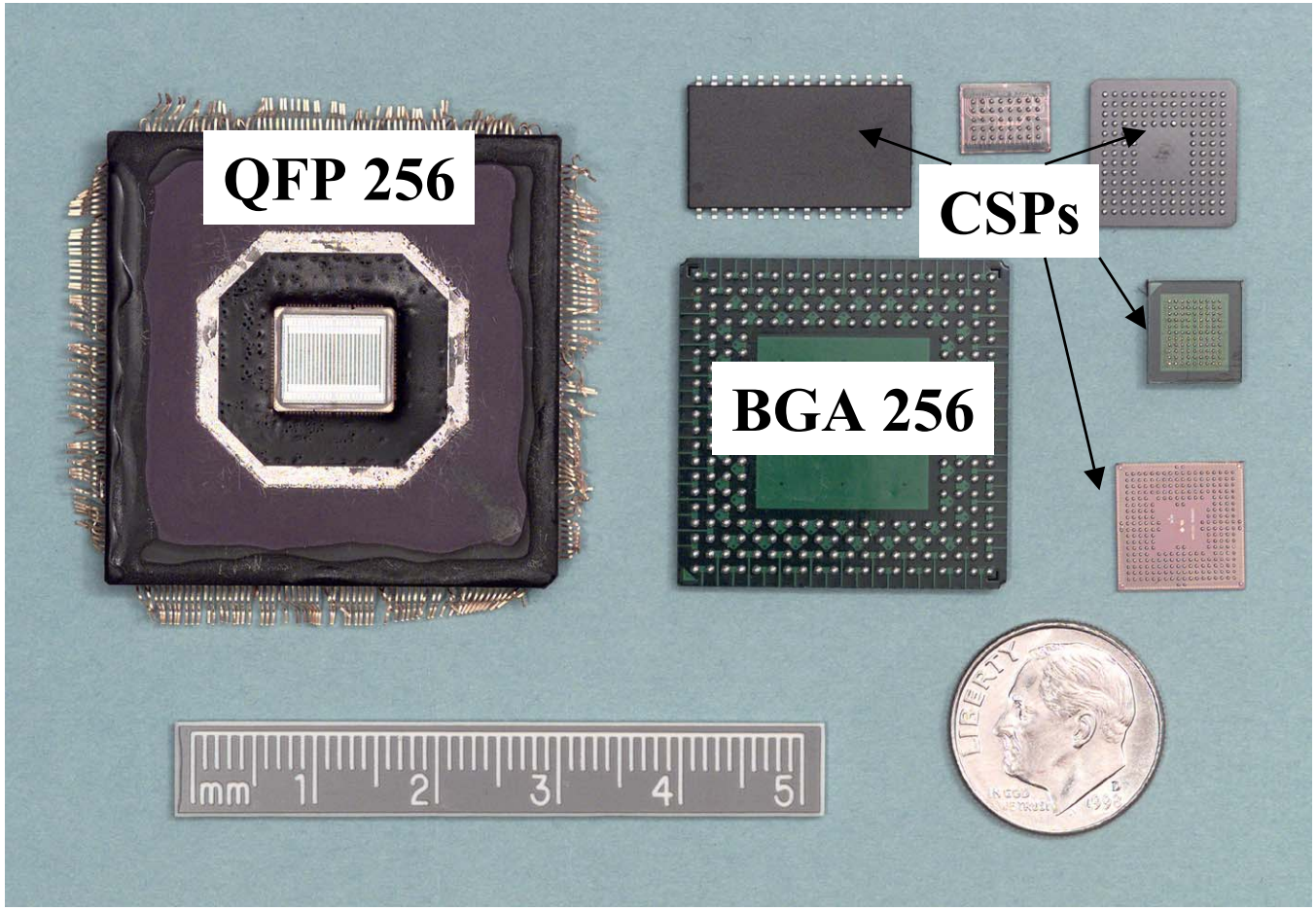
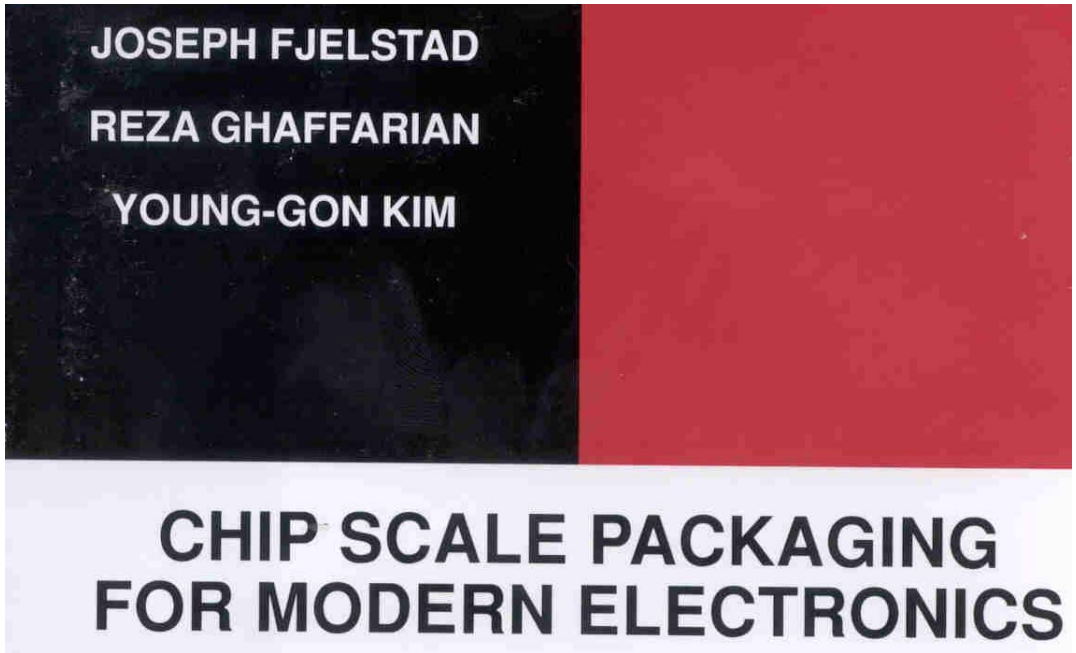
Outline

- Electronic Package Trend
  - Package shrink trends/BGA/CSP
  - CBGA and BGA definition
  - Qualification Approaches
  - IPC 9701
  - CBGA and BGA
- Reliability
  - Thermal cycle test results
  - Thermal cycle/vibration failure mechanisms
  - Conclusion
- Guides for NASA Missions

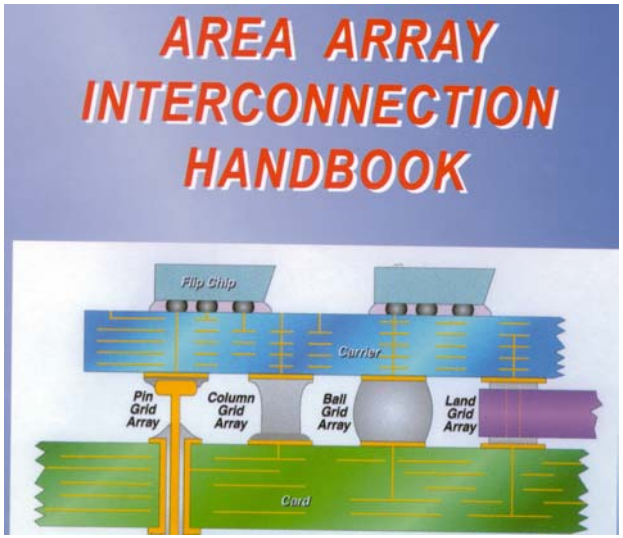
Package Miniaturization



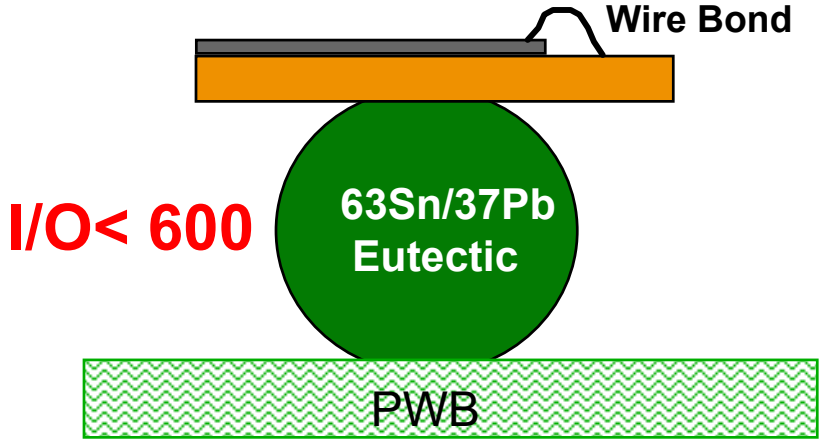
References


JOSEPH FJELSTAD
REZA GHAFFARIAN
YOUNG-GON KIM
CHIP SCALE PACKAGING
FOR MODERN ELECTRONICS

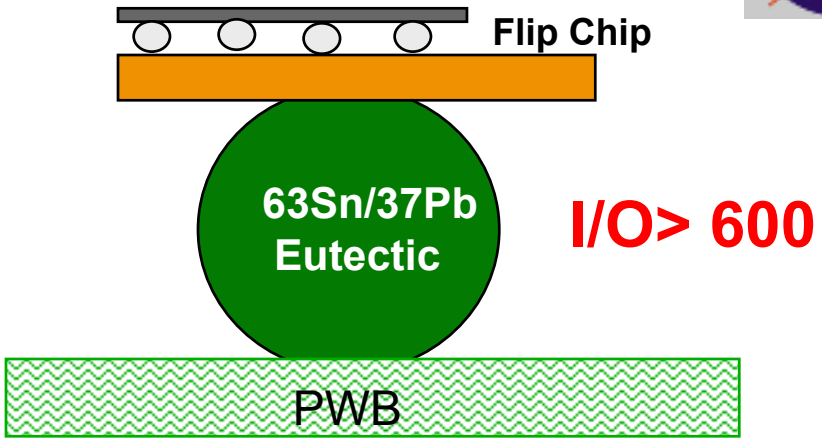
HANDBOOKS
AREA ARRAY
PACKAGING
HANDBOOK


AREA ARRAY
INTERCONNECTION
HANDBOOK
Flip Chip
Carrier
Pin Grid Array
Column Grid Array
Ball Grid Array
Land Grid Array
Card

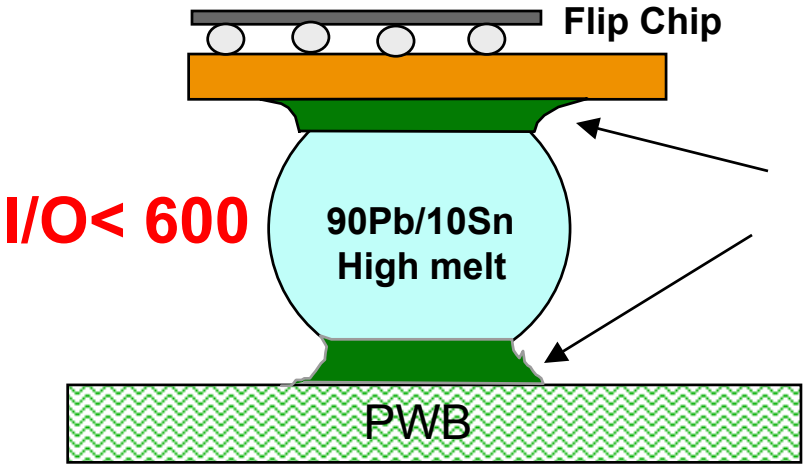
BGA Package Types



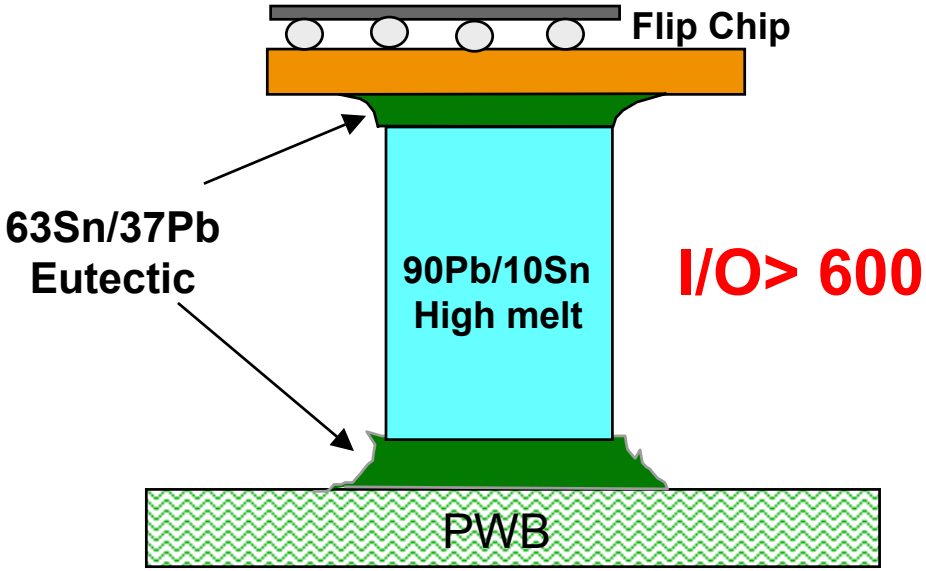
Plastic BGA (PBGA)



Flip Chip BGA (FCBGA)



Ceramic BGA (CBGA)

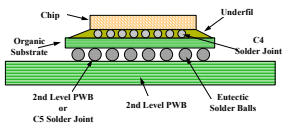


Column CBGA (CCGA)

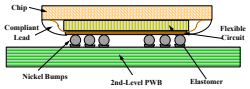
CSPs

Grid Arrays

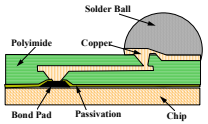
C4



Wire Bond



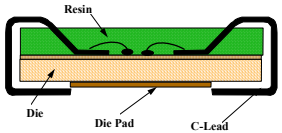
Wafer



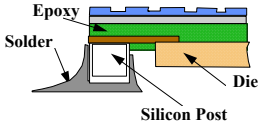
- High I/Os
- Wire bond I/O Limitation
- C4 ceramic, Wafer, Reliability?
- Assembly Robustness

Leads

Leaded



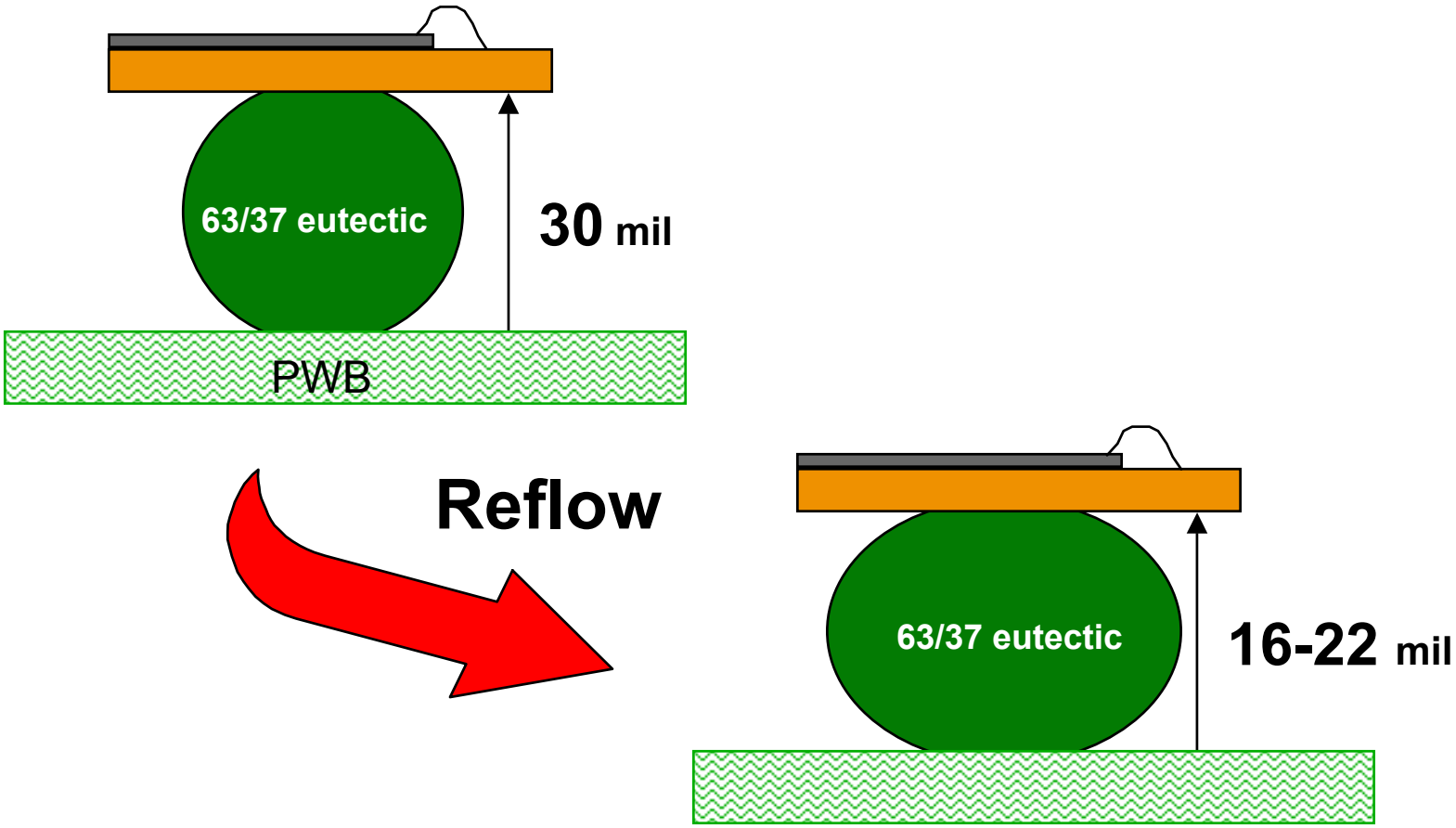
No Leads



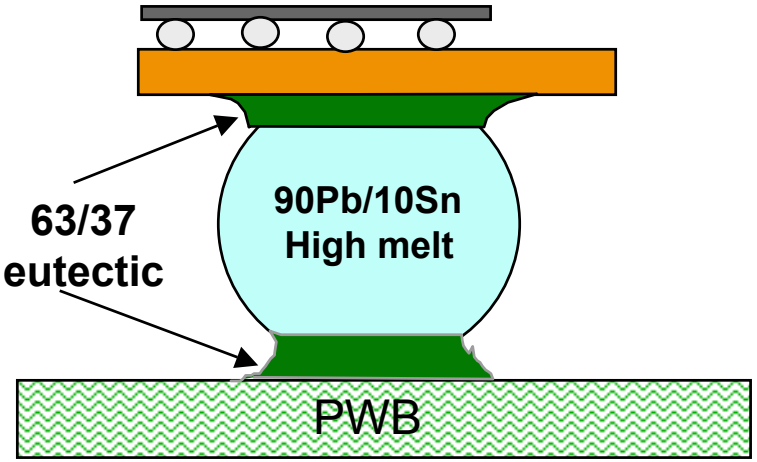
- Low I/Os
- No Leads, Reliability?
- Assembly Robustness?

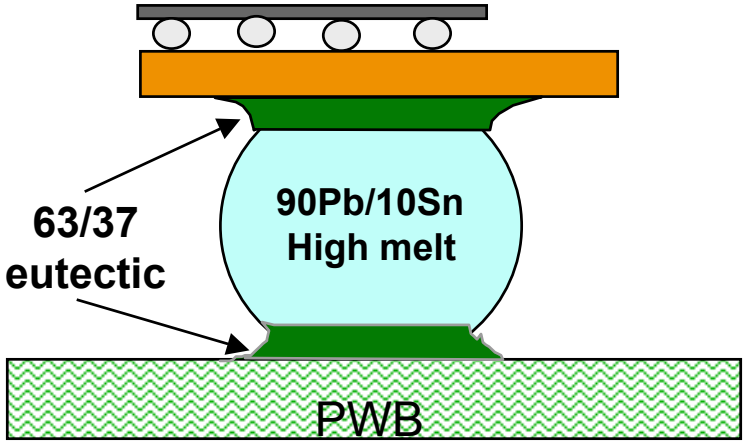
Self Alignment

BGA Balls Collapse



CBGA Balls Control Height





BGA vs QFP

- Advantages
  - Capable of high pin counts
  - Manufacturing robustness
  - Higher package densities
  - Faster circuitry speed than QFP
  - Better heat dissipation
- Challenges
  - **Inspection**
  - Routing for high pin count
  - Rework, individual balls

Qualification- IPC 9701

- IPC 9701, Released Jan 2002
  - IPC SM785- Guideline
    - No answer to the question of data for product application
    - Data comparison
  - IPC 9701
    - Details on thermal cycle test and acceptance
- Key Controls
  - Surface finish (OSP, HASL), thickness, 93 mil, NSMD, continuous monitor, etc.
- Five Cycle Conditions
  - Preference 0/100°C
- Five number of thermal cycles
  - Preference 6,000 cycles

IPC 9701- "Performance Test Methods and Qualification Requirements for Surface Mount Solder Attachments"

IPC 9701Temperature Cycle Requirements

Table 1 Temperature cycling requirements specified in Table 4.1 of IPC 9701

Test Condition	Mandated Condition
Temperature Cycle (TC) Condition: ***TC1***	***0°C ↔ +100°C (Preferred Reference)***
TC2	–25°C ↔ +100°C
TC3	–40°C ↔ +125°C
TC4	–55°C ↔ +125°C
TC 5	-55 °C<-> 100°C
Test Duration	Whichever condition occurs FIRST: 50% ***(preferred 63.2%)*** cumulative failure (Preferred Reference Test Duration) or
Number of Thermal Cycle (NTC) Requirement: NTC-A	200 cycles
NTC-B	500 cycles
NTC-C	1,000 cycles (Preferred for TC2, TC3,and TC4)
NTC-D	3,000 cycles
NTC-E	***6,000 cycles (Preferred Reference TC1***)
Low Temperature Dwell	10 minutes
Temp. tolerance (preferred)	+0/–10°C (+0/–5°C) [+0/–18°F (+0/–9°F)]
High Temperature Dwell	10 minutes
Temp. tolerance (preferred)	+10/–0°C (+5/–0°C) [+18/–0°F(+9/–0°F)]

Test Vehicles

Type 1 "300" I/Os

- 352 Plastic Perimeter SuperBGA 35 mm
- 361 Ceramic Full Array 25 mm
- 352 Plastic Perimeter OMPAC 35 mm
- 313 Plastic Full Array OMPAC 35 mm

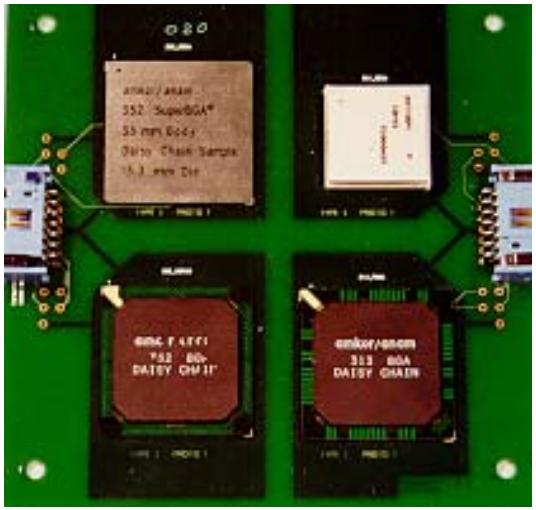
361 I/O CBGA

Type 2 "600" I/Os

- 560 Plastic Perimeter SuperBGA 42mm
- 625 Ceramic Full Array 32.5 mm
- 256 Plastic Gull Wing 30.6 mm
- 256 Plastic Perimeter OMPAC 27 mm

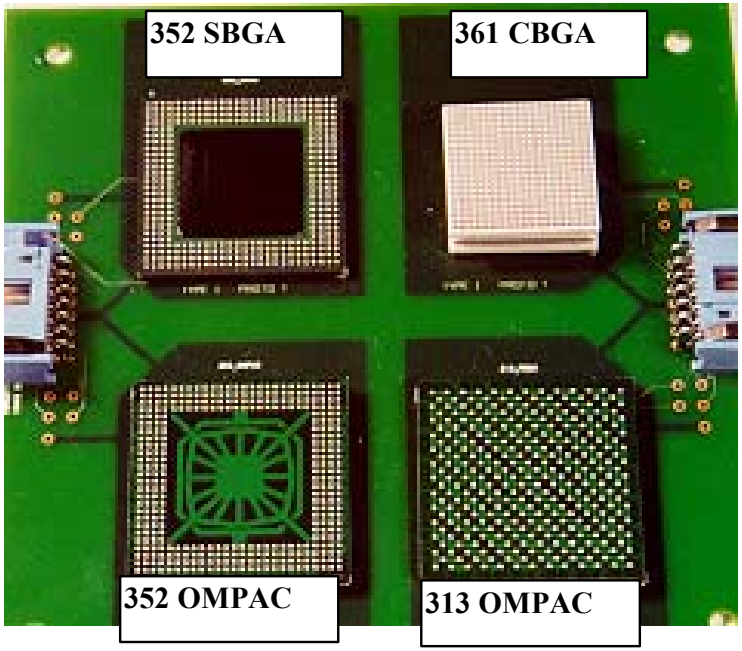
625 I/O CBGA

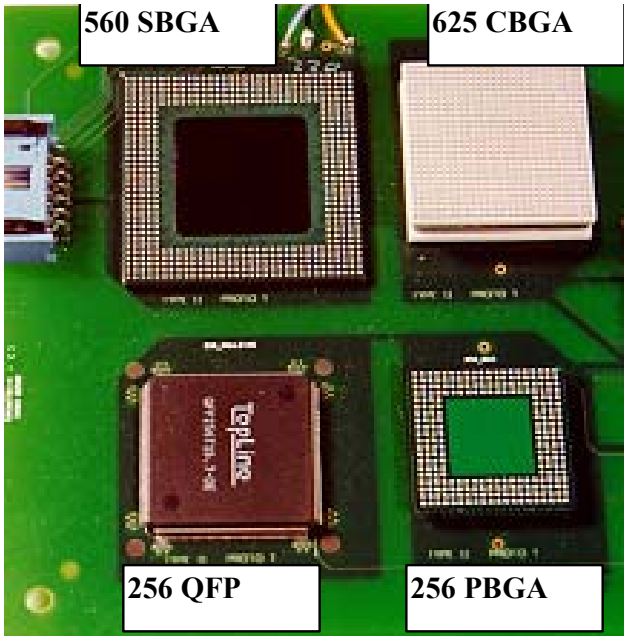
BGA Test Vehicles



a) Type 1 Test Vehicles, 300 I/Os

b) Type 2 Test Vehicles, 600 I/Os



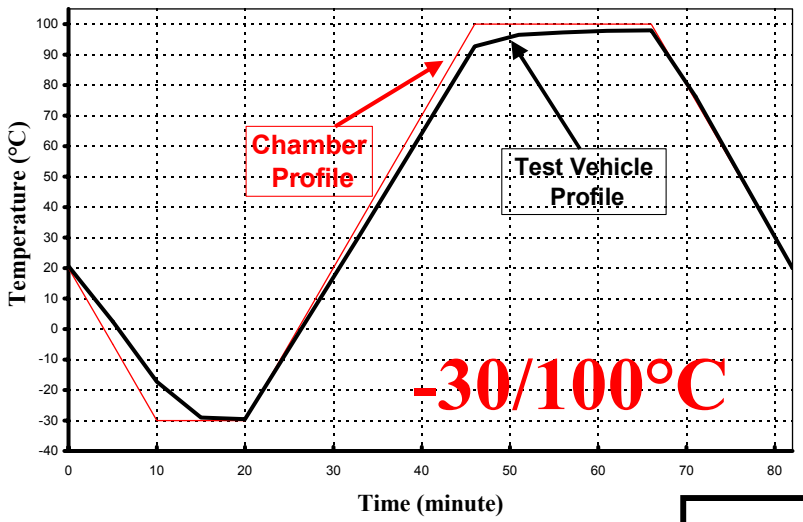


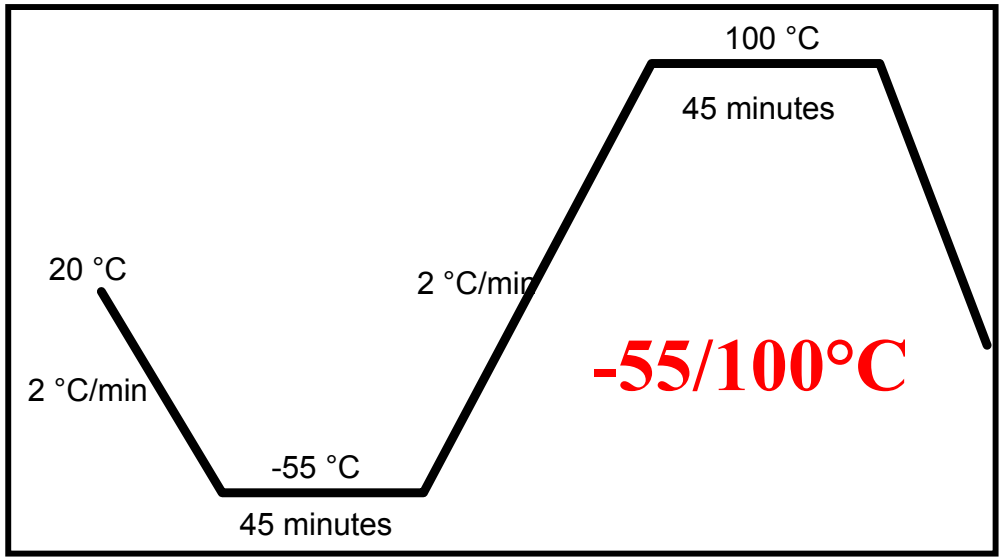
Thermal Cycle Profiles

- **Mid Range**
  - **Cycle A, -30 to 100°C, 82 min.** (2-5°C/min, 10 min. dwells)
  - **Cycle B, -55 to 100°C, 245 min.** (2-5°C/min, 45 min. dwells)

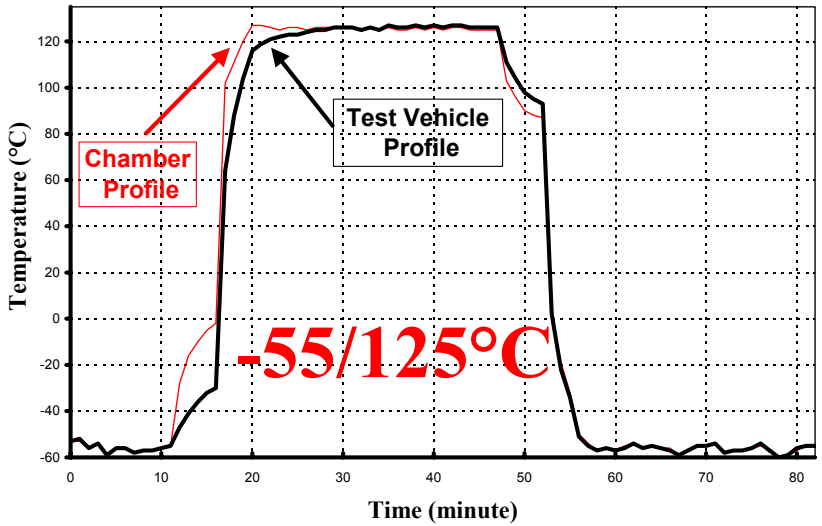
- **Military**
  - **Cycle C, -55 to 125°C, 159 min.** (2-5°C/min., 10 min. dwells)
  - **Cycle D, -55 to 125°C, 68 min.** (high heat/cool, 20 min. dwells)

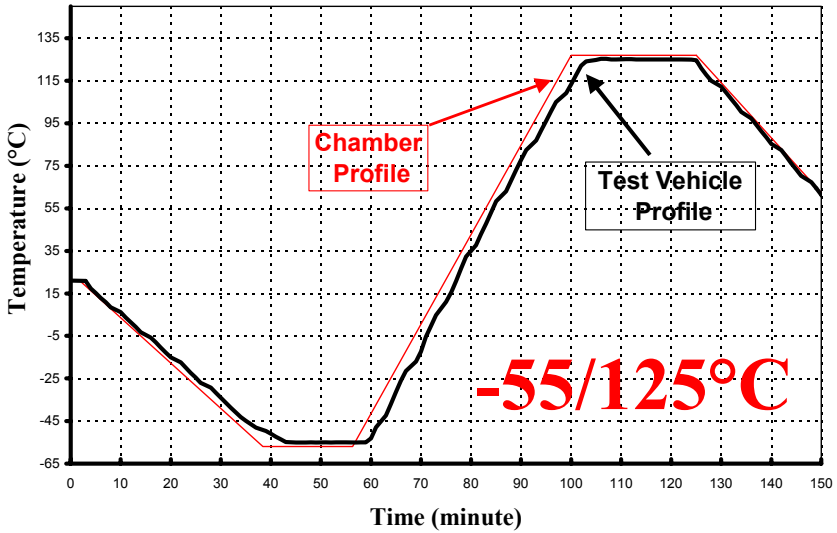
Thermal Cycle Profiles
Mid Ranges

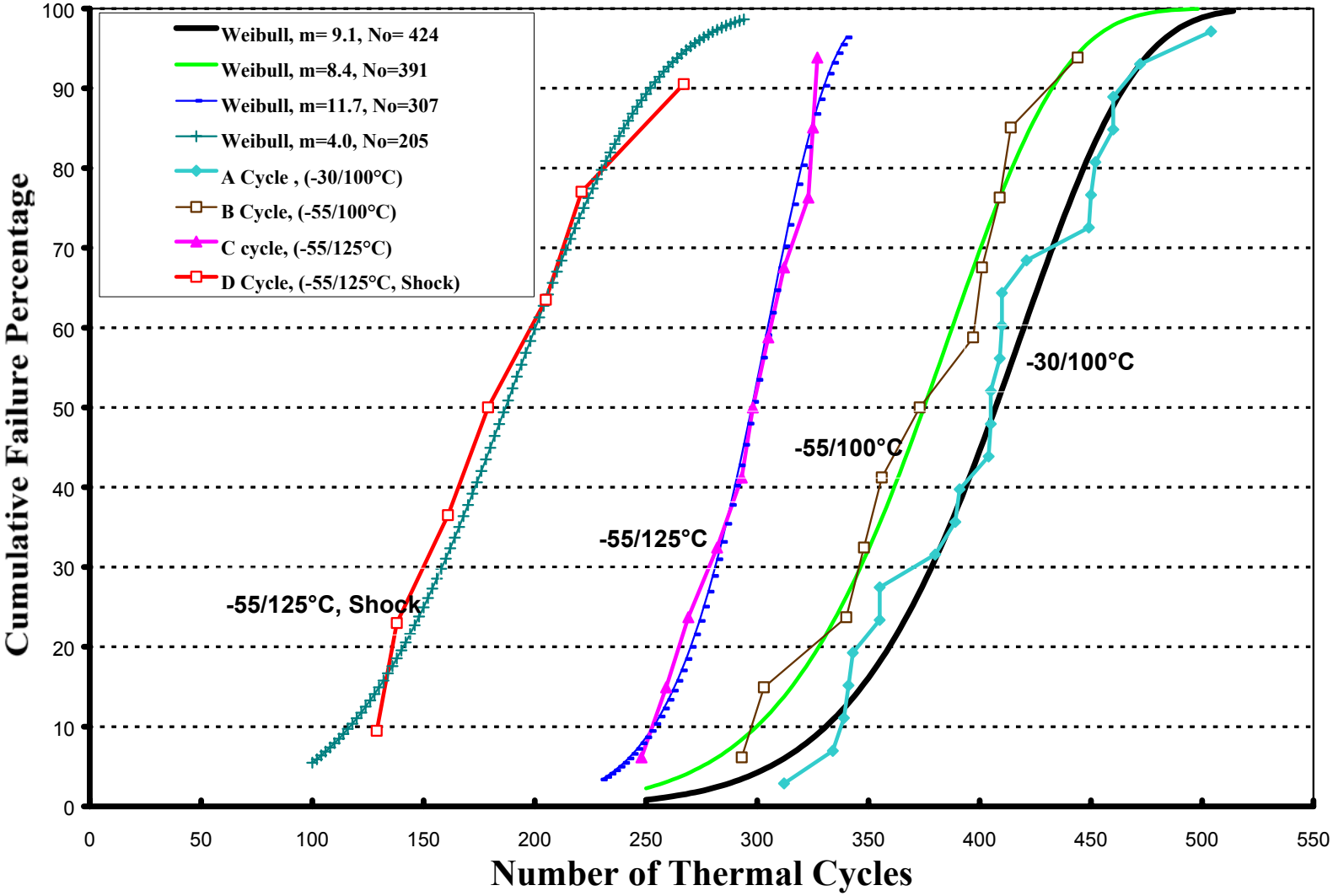




Thermal Cycle Profiles
Military






Weibull, m= 9.1, No= 424
Weibull, m=8.4, No=391
Weibull, m=11.7, No=307
Weibull, m=4.0, No=205
A Cycle , (-30/100°C)
B Cycle, (-55/100°C)
C cycle, (-55/125°C)
D Cycle, (-55/125°C, Shock)
-55/125°C, Shock
-55/125°C
-55/100°C
-30/100°C
Cumulative Failure Percentage
Number of Thermal Cycles
0
10
20
30
40
50
60
70
80
90
100
0
50
100
150
200
250
300
350
400
450
500
550

Weibull CDF

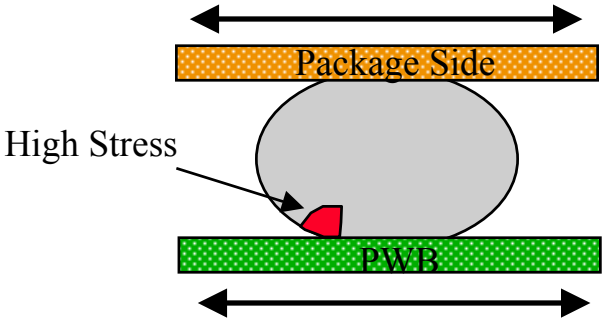
2-P and 3-P Weibull (Cumulative Distribution Function)

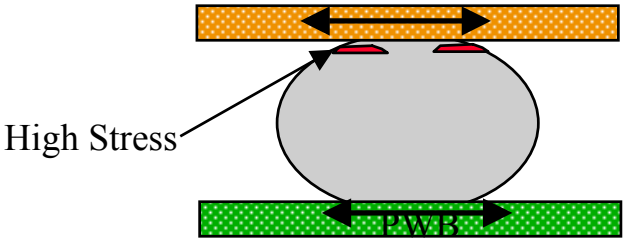
$$F(N) = 1 - \exp -[(N - N_1)/N_o]^m$$

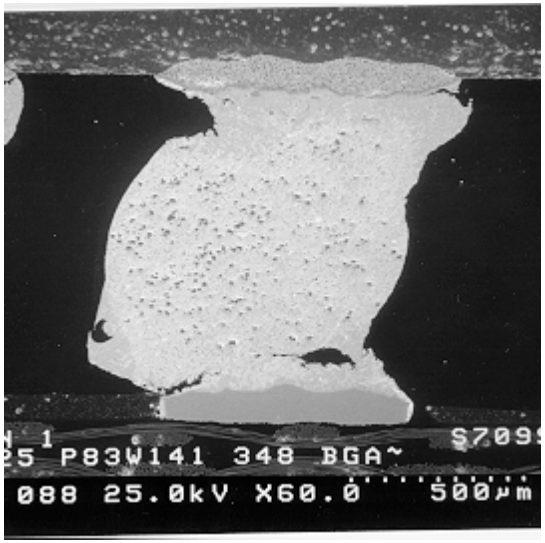
where

- F(N) is the cumulative failure distribution function
- N is the number of thermal cycles
- N_o is a scale parameter that commonly is referred to as characteristic life, and is the number of thermal cycles with a 63.2% failure occurrence.
- N_1 is the failure free cycles for a 3-parameter Weibull distribution
- m is the shape parameter and for a large m is approximately inversely proportional to the coefficient of variation (CV) by 1.2/CV; that is, as m increases, the spread in cycles to failure decreases

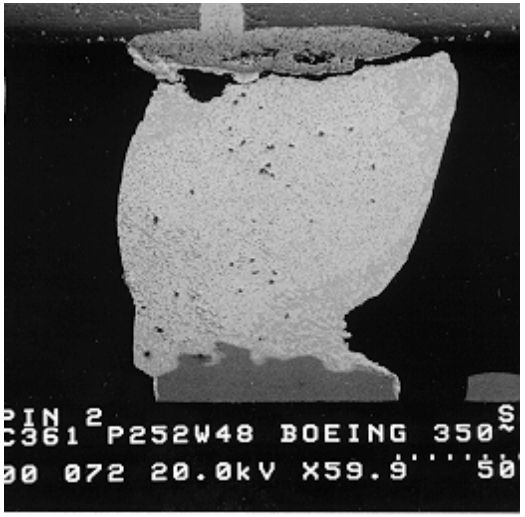
Failure Mechanisms
Thermal Cycle Only





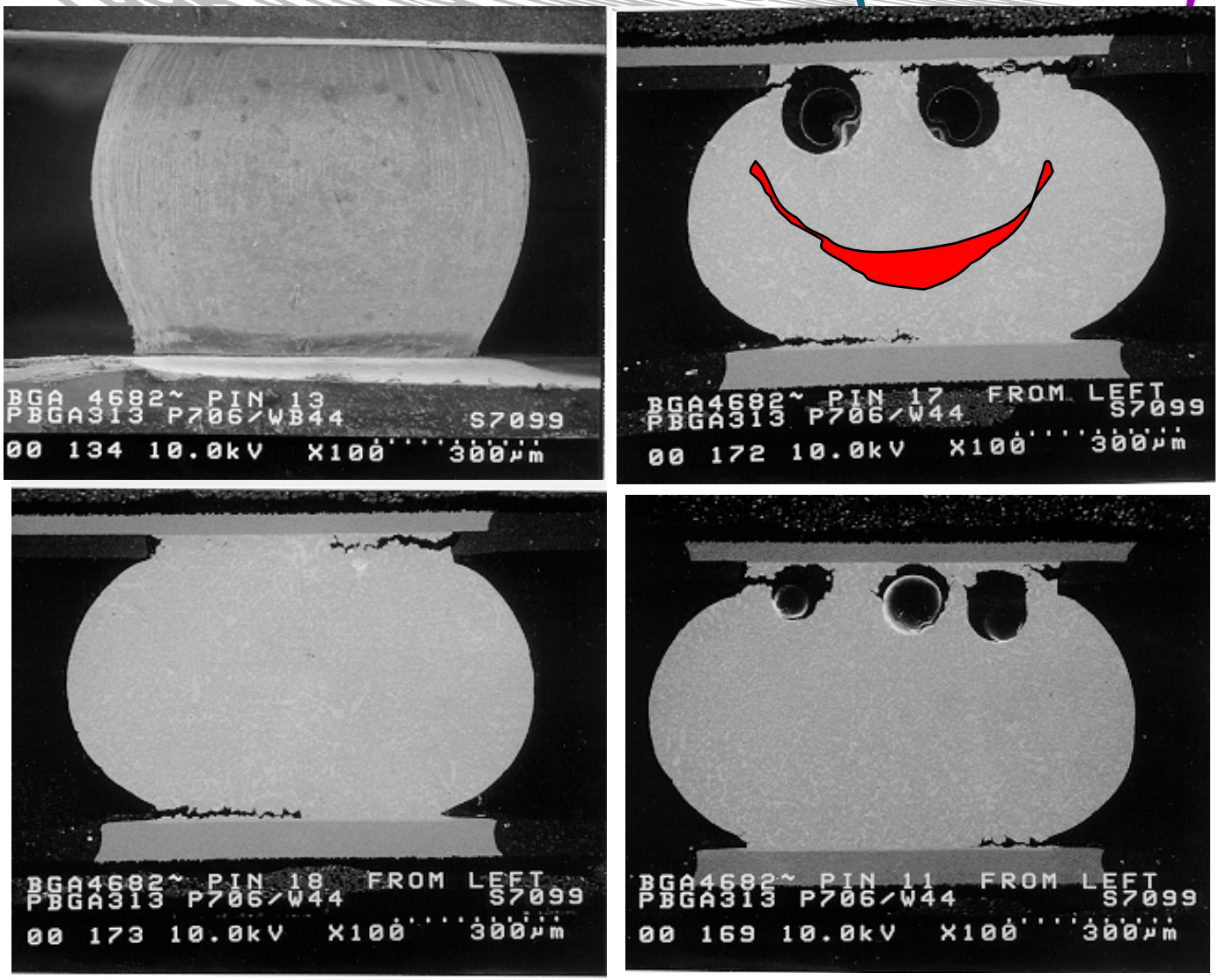


Global CTE Mismatch
-30°C<>100°C



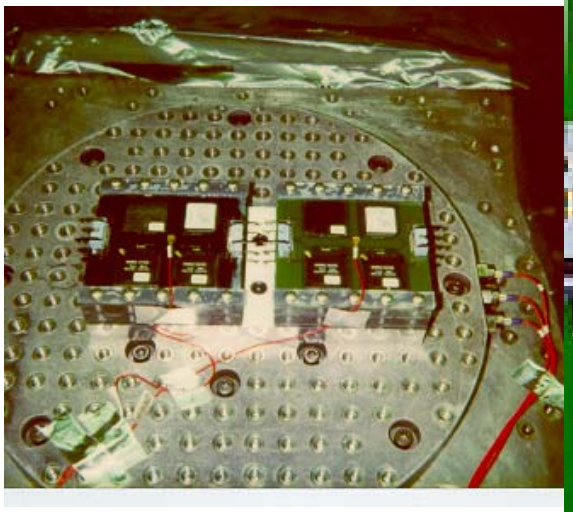
Local CTE Mismatch
-55°C<>125°C

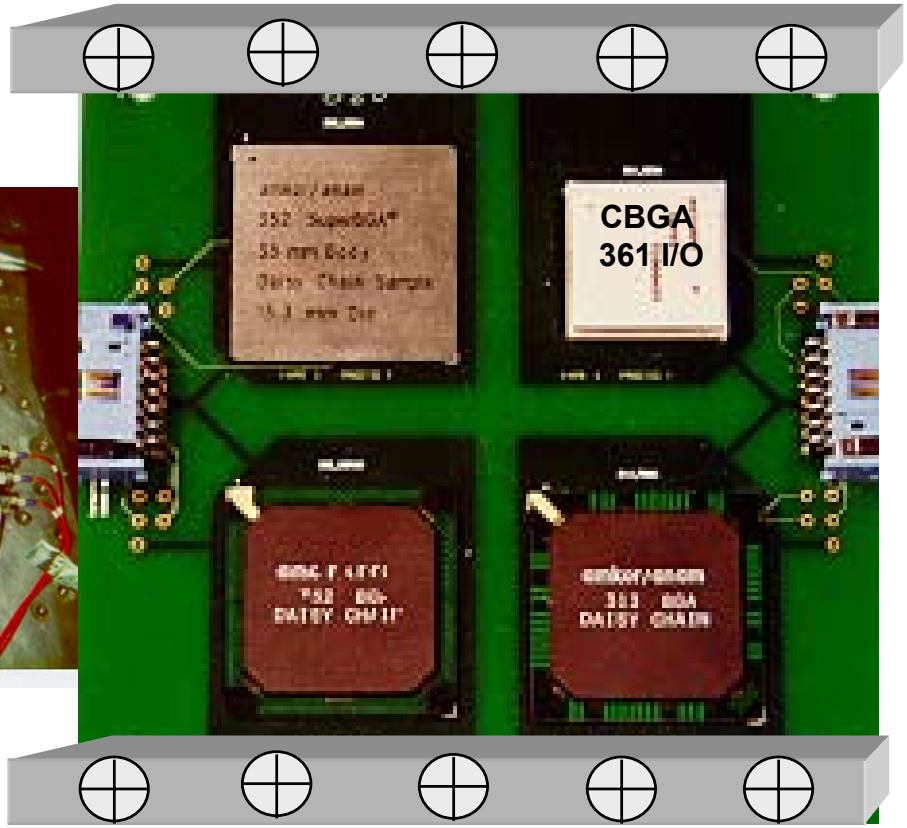
PBGA 313 I/O Failure (-30/100C)



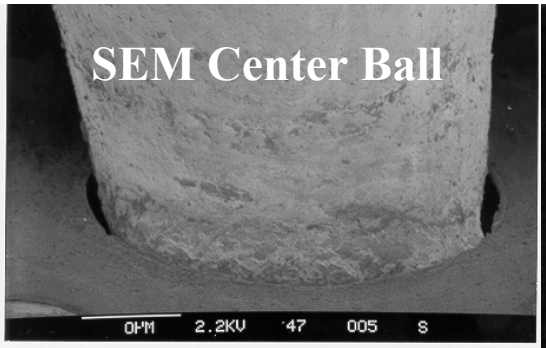
(-30/100°C, 4692 JPL cycles, failure

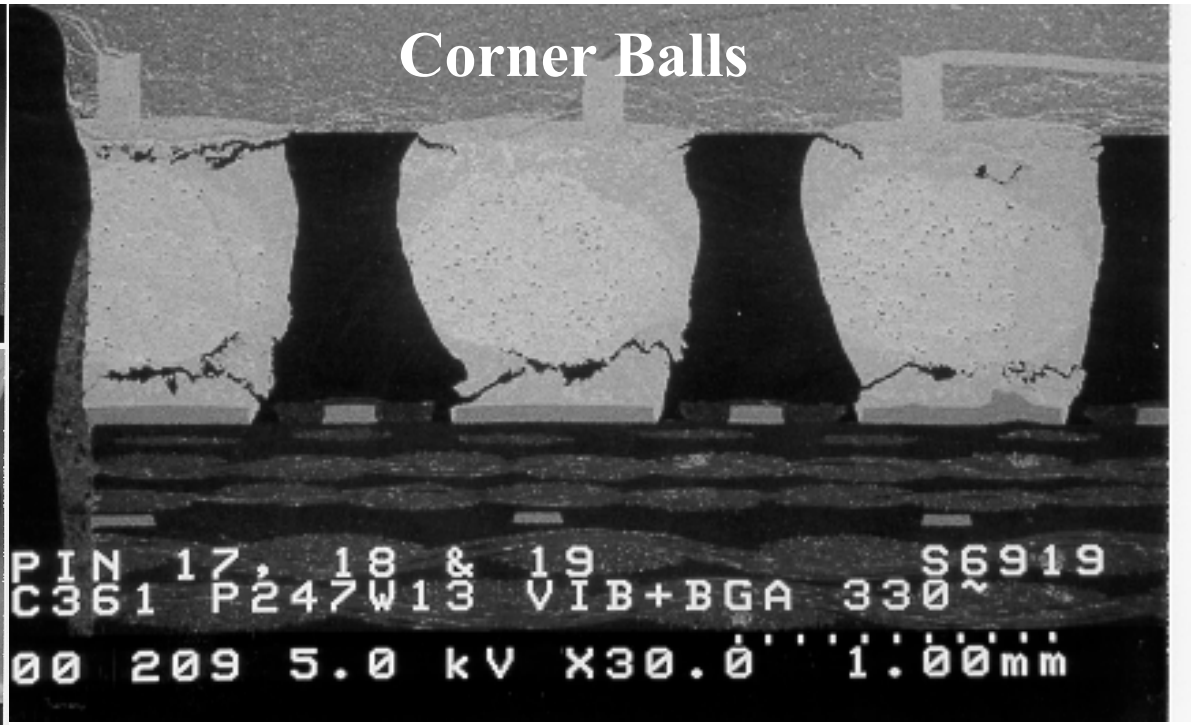
Vibration Setup





Failure Mechanisms
Vibration + Thermal cycle





Conclusions

- A near-thermal shock in the range of -55°/125°C induced the most damage
  - Up to 50% reduction compared to thermal cycle conditions
- Assemblies with three levels of rigidity passed a launch environment
  - Cycles-to-failure after vibration significantly affected by board rigidity
  - >50% reduction in cycles-to-failure for a less rigid board
- Failure for thermal cycle were from board/package
- Failure for random vibration
  - Tensile deformation in high melt balls
  - Tensile shear in eutectic solder

BGA Qualification

NASA Missions

NEPP BGA Report

- NEPP Web site, BGA Technology Readiness
- http://nepp.nasa.gov/index_nasa.cfm/778
  - Search: Reza Ghaffarian BGA NEPP Technology

- Provide Overview of BGA/CSP Technologies
- Key parameters affecting reliability
- Procedures for Qual using IPC/others
- Missions are categorized
- PWB/package assembly/underfill
- Radiation

Qualification -1

- **Review IPC Standards**
  - IPC 7095, design and assembly process implementation for BGA
  - IPC 9701
  - www. IPC.org
- **Define Overall NASA Requirements**
  - Radiation, mechanical, thermal, life cycle, etc.
- **Determine Appropriate BGA/CGA/CSP**
  - I/O, build up, solder geometry, materials, heat distribution, etc.
- **Is Package Tech within Mission Env.**
  - Die radiation capability, temp limits including Tg, junction temp.
- Life Thermal Cycle Qual- 3 times realistic worst case

Qualification - 2

- **Four Mission Categories**
  - **A: Benign thermal cycle and short mission**
  - **B: Benign thermal cycle and long mission**
  - **C: Extreme thermal cycle and short mission**
  - **D: Extreme thermal cycle and long mission**

- **If No Details, Use Rules-of-Thumb**
  - **For A and B, life cycles 100-500 NASA cycles (-55/100°C)**
  - **For C and D, estimate flight allowable temp ranges plus the ground and multiply mission life cycles by 3**

Qualification - 3

- **Review Qualification Data by Vendor**
  - Most plastic BGAs on polymeric boards have sufficient life cycle to meet the A and B NASA requirements
  - Plastic package with large die may be required to qualify for B
  - Low I/O ceramic sufficient life for A
  - High I/O may not meet either B or even A mission categories
- **Most BGA need to be qualified for C and D missions**
- **Most Ceramic and plastic CSPs may meet the A mission, but need PQV for B,C, and D missions**
- **Package Qualification Verification (PQV) test vehicle**
- **Others including Radiation/Vibration/Shock**

SUMMARY

- No Flight Heritage Data Yet
- BGAs and CSPs Less 2nd Level (Assembly) Thermal Cycles Than Leaded Counterparts
- CSPs Have Lower Life Than BGAs
- Perform Tests on Dummy Daisy Chain Package/Board, if in Doubt
- Non-destructive Technique for Interconnection is not Yet Developed
- Most Packages Are Built for Commercial Applications and Many Issues with COTS BGAs/CSPs are similar to those for conventional COTS

Acknowledgments

NASA Electronic Part and Packaging (NEPP)

In-kind contributions of team members

BGA CONSORTIUM